## In the Specification:

Please amend the specification as follows:

Please replace the last paragraph on page 12 with the following paragraph.

Examples of ligands where the bridging group comprises a trimethylene group connecting M¹ or M² of which the middle carbon atom in the bridge has two additional bondings with a non-hydrogen atom are disclosed in copending U.S. application Serial No. 10/287,731, filed November 4, 2002, now U.S. Patent No. 6,794,553, and WO 03/040065 (which are herein incorporated by referenced) and include:

2,2-dimethyl, 1,3-PP'bis(9-phosphabicyclo[3,3,1]nonyl)-propane;

2-methyl, 2-hydroxymethyl, 1,3-PP'bis(9-phosphabicyclo[3,3,1]nonyl)-propane;

2,2-dimethyl, 1,3-PP'bis(9-phosphabicyclo[4,2,1]nonyl)-propane;

2-methyl, 2-hydroxymethyl, 1,3-PP'bis(9-phosphabicyclo[4,2,1]nonyl)-propane; and mixtures thereof.

Please replace the first paragraph on page 13 with the following paragraph.

Examples of bidentatediphosphine ligands having a dimethylenebiphenyl bridge are described in copending U.S. application Serial No. 10/287,731, filed November 4, 2002, now U.S. Patent No. 6,794,553, and WO 03/040065 (which are herein incorporated by referenced) and include:

2,2'-bis-(1,4-cyclooctylene-phosphino-methyl)-1,1'-biphenyl;

2,2'-bis-(1,5-cyclooctylene-phosphino-methyl)-1,1'-biphenyl;

and mixtures thereof.